AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings, of claims in the application:

LISTING OF CLAIMS:

- 1. 7. (Canceled)
- 8. (New) An adhesive resin comprising a polyimide resin obtained by reacting a diamine component containing a diamine represented by the following formula (1) as an essential component with a tetracarboxylic dianhydride component,

wherein the diamine component further comprises a diamine represented by the following formula (2) as a diamine component,

$$H_2N - R1 - \left\{S \begin{vmatrix} R2 & R4 \\ -O - \\ -In \end{vmatrix} S - R6 - NH_2 \right\}$$
(2)

(wherein R1 and R6 are divalent aliphatic groups having 1 to 4 carbon atoms or aromatic groups; R2 to R5 are monovalent aliphatic groups or aromatic groups; and n is an integer of 0 to 20)

and/or the tetracarboxylic dianhydride component further comprises a tetracarboxylic dianhydride represented by the following formula (3) as the tetracarboxylic dianhydride component,

$$\begin{array}{c|ccccc}
O & R8 & R10 & 0 \\
C & R7 & Si & O & C \\
O & R9 & R11 & C & O
\end{array}$$
(3)

(wherein R7 and R12 are trivalent aliphatic groups or aromatic groups; R8 to R11 are monovalent aliphatic groups or aromatic groups; the carbon skeleton of the acid anhydride structure is a 5- or 6-membered ring; and n is an integer of 0 to 20).

9. (New) The adhesive resin according to Claim 8, wherein the diamine represented by the formula (1) comprises a diamine represented by the following formula (4)

- 10. (New) The adhesive resin according to Claim 8 comprising a thermosetting resin except a polyimide resin.
- 11. (New) The adhesive resin according to Claim 8, wherein the thermosetting resin comprises an epoxy resin, and the adhesive resin further comprises an epoxy resin-curing agent.
- 12. (New) The adhesive resin according to Claim 8 comprising inorganic filler.

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- 13. (New) A film adhesive comprising the adhesive resin according to Claim8.
- 14. (New) A semiconductor device wherein a semiconductor element is attached to a support by the film adhesive according to Claim 6.